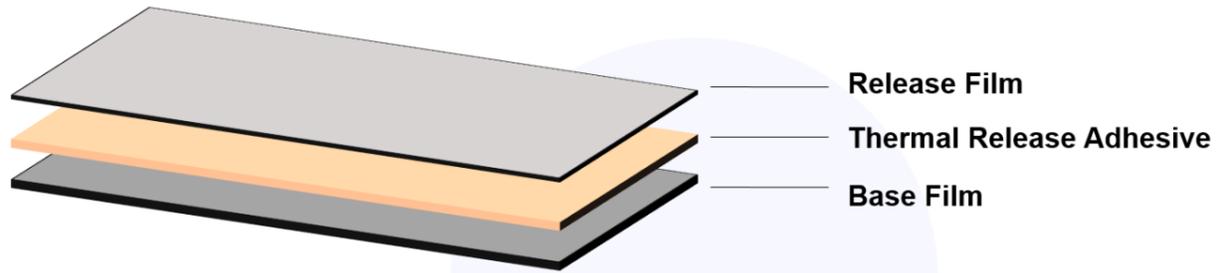


## Application

- MLCC cutting process
- LED chip grinding process
- Glass cutting process
- Chip/Component dicing process
- Use for temporary fixed purpose



## Feature

- Make for semiconductor device 、 electronic component 、 optoelectronics 、 LED 、 MLCC component cutting or grinding process.
- Qualities have been certificated by international leading companies.
- Excellent adhesion, no position shift when cutting tiny components.
- Electronic components are easily released from tape after heating by hot plate or oven.
- It shows excellent performance and stability in MLCC & others electronic component manufacturing industry.

Model	Process	Base film material	Color	Thermal release temperature (°C)
TR-120B	Protecting process	PET	Milky white/Light yellow	120
TR-51PA2	MLCC component 、 LED chip 、 electronic component 、 LCD glass panel cutting & Sapphire substrate thinning process			100
TR-120A				120
TR-561A2				130
TR-150A2				150
TR-170A2				170

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